

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Robert F. Wallace
Assignee: SanDisk Corporation
Title: Semiconductor Package Using Terminals Formed on a
Conductive Layer of a Circuit Board
Serial No.: Unassigned Filed: May 24, 2001
Examiner: Unknown Group Art Unit: Unknown
Docket No.: M-10238-2C US

San Francisco, California
May 24, 2001

BOX PATENT APPLICATION
ASSISTANT COMMISSIONER FOR PATENTS
Washington, D. C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Please amend the above-identified continuation patent application as follows:

IN THE SPECIFICATION

Please amend the specification by inserting on Page 1, line 4, before "Field of the
Invention" the following heading and added paragraph:

--CROSS-REFERENCE TO RELATED APPLICATIONS

This is a continuation of U.S. Application Serial No. 09/487,106, filed January
19, 2000, ^{now US Patent 6410355} entitled "Semiconductor Package Using Terminals Formed on a Conductive
Layer of a Circuit Board" by Robert F. Wallace which is a divisional of U.S.

Application Serial No. 09/906,140 filed on June 11, 1998, now U.S. Patent No.